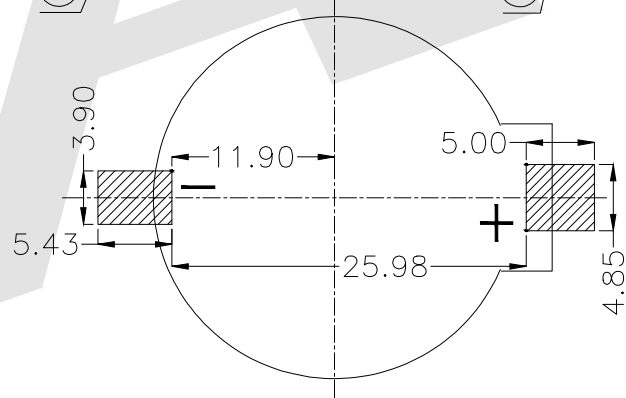
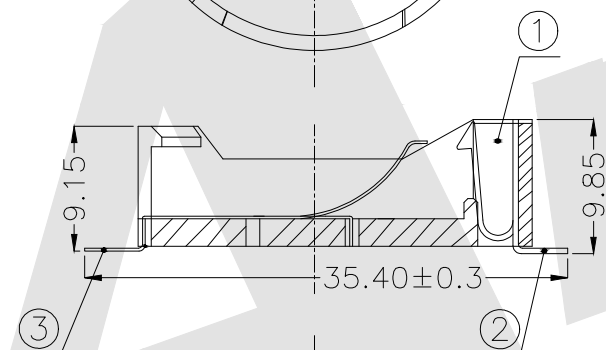
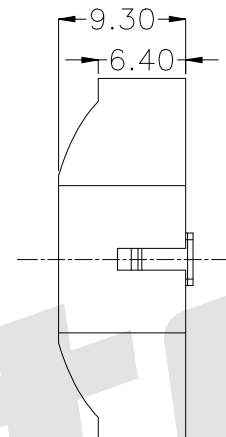
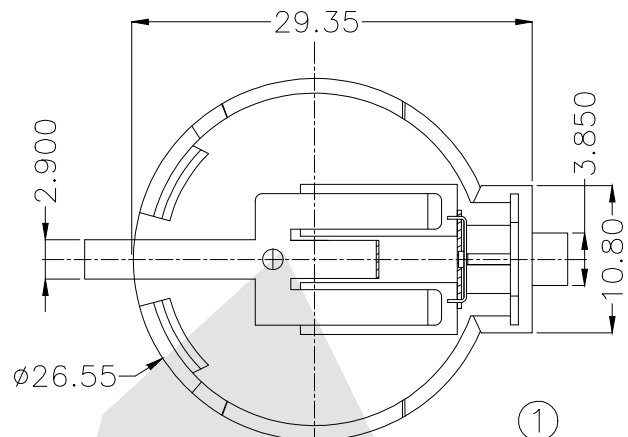


HSF



PCB Layout Diagram  
Top View

NOTE:

1, Material:

- a. Housing: PA10T
  - b. Contact: PHOSPHOR BRONZE  
(Surface Plating: Si 3u")
- See Ordering Information

2, Electric:

- a. Contact Resistance: 30 Milliohms Max
- b. Insulation Resistance: 1000 MEGA OHMS Min
- c. Dielectric Voltage: 500V AC One Sea Level
- d. Operating Temperature: -55° To +85°

Order code:

BT - M - SN - R - CR2450E  
① ② ③ ④ ⑤

- ① BT: Coin Cell Holders
- ② Appearance For The Product  
M: SMT TYPE
- ③ Contact Plating  
SN: Tin  
G0: Gold Flash  
G1: 3U" Gold  
G2: 5U" Gold  
G3: 10U" Gold  
G4: 15U" Gold  
G5: 30U" Gold
- ④ Packing Method  
A: Tray Packing  
R: Tape & Reel Packing
- ⑤ Product Number  
CR2450E

Unless Otherwise specified tolerance  
X. ±0.35 X.XX: ±0.20  
X.X: ±0.25 X.XXX: ±0.15

**Antenk**® ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail: sales@antenk.com

SCALE: As Shown UNIT: mm  
DRAW Wu Feng Rong DATE 07/09/2021  
CHECK BobYang DATE 07/09/2021  
3rd ANGLE PROJECTION

TITLE: Coin Cell Holders SMT For CR2450E

DRAWING NO: BT-M-SN-R-CR2450E

PRODUCT NO: BT-M-SN-R-CR2450E

TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.20mm	Si Plating
TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.40mm	Si Plating
HOUSING	1	PA10T	BLACK
PART NAME	Q'TY	MATERIAL	PLATING & COLOR